

In The Claims:

Please amend the claims as follows (all pending claims are listed for the Examiner's convenience):

19. (Currently Amended) A process for making a cured film having the memory of a specified shape, said process comprising the steps of:

providing an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature no higher than 50° °C after polymerization;

providing a low-molecular weight compound that has in its molecule one reactive double bond capable of polymerization with said oligomer compound and that has a glass transition temperature higher than at least 90° °C after polymerization;

forming a resin composition from said oligomer compound and ~~said mixture~~ said low-molecular weight compound,

shaping said resin composition by either applying it onto a shaped part or placing it between films,

curing said resin composition with electron beams; and

removing the cured composition from the shaped part or films.

20. (Currently Amended) A process for making a cured film having the memory of a specified shape, said process comprising the steps of:

providing an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature no higher than 50° °C after polymerization;

providing a mixture of two or more low-molecular weight compounds that have in their molecule one reactive double bond capable of copolymerization with said oligomer compound and that have a glass transition temperature higher than 90° °C after polymerization;

forming a resin composition from said oligomer compound and said mixture,

shaping said resin composition by either applying it onto a shaped part or placing it between films,

curing said resin composition with electron beams; and
removing the cured composition from the shaped part or films.

21. (Currently Amended) A process for making a cured film having the memory of a specified shape, said process comprising the steps of:

providing an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature no higher than 50° C after polymerization;

providing a simple urethane adduct of hydroxyethyl acrylate or hydroxyethyl metacrylate and a diisocyanate;

providing an optional low-molecular weight compound that has in its molecule at least one double bond capable of copolymerization with the oligomer compound;

forming a resin composition from said oligomer compound, said simple urethane adduct said low-molecular weight compound,

shaping said resin composition by either applying it onto a shaped part or placing it between films,

curing said resin composition with electron beams; and
removing the cured composition from the shaped part or films.